MOSFET - N-Channel Shielded Gate PowerTrench® 150 V, 7.9 mΩ, 95.6 A

NTMFS7D5N15MC

Features

- Small Footprint (5 x 6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low QG and Capacitance to Minimize Driver Losses
- 100% UIL Tested
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Synchronous Rectification
- AC-DC and DC-DC Power Supplies
- AC-DC Adapters (USB PD) SR
- Load Switch

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

| Parameter | | Symbol | Value | Unit | |
|---|----------------------|-----------------------------------|-----------------|-------|----|
| Drain-to-Source Voltage | | V _{DSS} | 150 | V | |
| Gate-to-Source Voltage | | V _{GS} | ±20 | V | |
| Continuous Drain Current R _{θJC} (Note 2) | Steady | T _C = 25°C | I _D | 95.6 | Α |
| Power Dissipation $R_{\theta JC}$ (Note 2) | State | | P _D | 166.7 | W |
| Continuous Drain Current R _{0JA} (Notes 1, 2) | Steady State | ' . = 95°(' | I _D | 13.5 | Α |
| Power Dissipation R _{θJA} (Notes 1, 2) | | | P _D | 3.3 | W |
| Pulsed Drain Current | T _C = 25° | °C, t _p = 100 μs | I _{DM} | 478 | Α |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | -55 to +175 | °C | |
| Single Pulse Drain-to-Source Avalanche Energy (I _L = 18 A _{pk} , L = 3 mH) | | | | 486 | mJ |
| Lead Temperature for Soldering Purposes (1/8" from case for 10 s) | | TL | 260 | °C | |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

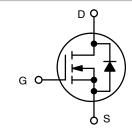
- 1. Surface-mounted on FR4 board using a 1 in2, 2 oz. Cu pad.
- 2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.



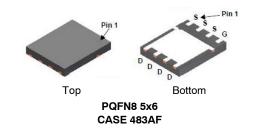
ON Semiconductor®

www.onsemi.com

| V _{(BR)DSS} | R _{DS(ON)} MAX | I _D MAX |
|----------------------|-------------------------|--------------------|
| 150 V | 7.9 m Ω @ 10 V | 95.6 A |



N-CHANNEL MOSFET



MARKING DIAGRAM



7D515M = Specific Device Code

= Assembly Location

Υ = Year W = Work Week 77 = Lot Traceability

ORDERING INFORMATION

| Device | Package | Shipping [†] | | |
|------------------------|----------|-----------------------|--|--|
| NTMFS7D5N15MC | Power 56 | 3000 / Tape | | |
| (Pb-Free/Halogen Free) | (PQFN8) | & Reel | | |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL RESISTANCE MAXIMUM RATINGS

| Parameter | Symbol | Value | Unit | |
|---|---------------|-------|------|--|
| Junction-to-Case - Steady State (Note 2) | $R_{	hetaJC}$ | 0.9 | °C/W | |
| Junction-to-Ambient - Steady State (Notes 1, 2) | $R_{	hetaJA}$ | 45 | | |

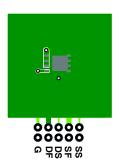
ELECTRICAL CHARACTERISTICS (T_{.1} = 25°C unless otherwise noted)

| Parameter | Symbol | Test Condition | | Min | Тур | Max | Unit |
|--|-------------------------------------|--|-----------------------|-----|------|------|-------|
| OFF CHARACTERISTICS | | | | | • | | • |
| Drain-to-Source Breakdown Voltage | V _{(BR)DSS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | | 150 | | | ٧ |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | V _{(BR)DSS} / | I _D = 250 μA, ref to 25°C | | | 83 | | mV/°C |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{GS} = 0 V, V _{DS} = 120 V | T _J = 25°C | | | 1.0 | μΑ |
| Gate-to-Source Leakage Current | I _{GSS} | V _{DS} = 0 V, V _{GS} | = ±20 V | | | ±100 | nA |
| ON CHARACTERISTICS | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | $V_{GS} = V_{DS}, I_D = 295 \mu\text{A}$ | | 2.5 | | 4.5 | V |
| Negative Threshold Temperature Coefficient | V _{GS(TH)} /T _J | I _D = 295 μA, ref to 25°C | | | -8.3 | | mV/°C |
| Drain-to-Source On Resistance | R _{DS(on)} | V _{GS} = 10 V, I _D = 54 A | | | 6.4 | 7.9 | mΩ |
| Drain-to-Source On Resistance | R _{DS(on)} | V _{GS} = 8 V, I _D = 27 A | | | 6.9 | 9.2 | mΩ |
| Forward Transconductance | 9FS | V _{DS} = 10 V, I _D = 54 A | | | 91 | | S |
| CHARGES, CAPACITANCES & GATE RESIS | STANCE | | | | | | |
| Input Capacitance | C _{ISS} | V _{GS} = 0 V, f = 1 MHz, V _{DS} = 75 V | | | 3835 | | pF |
| Output Capacitance | C _{OSS} | | | | 1070 | | |
| Reverse Transfer Capacitance | C _{RSS} | | | | 11 | | |
| Gate-Resistance | R_{G} | | | | 0.6 | 1.2 | Ω |
| Total Gate Charge | Q _{G(TOT)} | V _{GS} = 10 V, V _{DS} = 75 V; I _D = 54 A V _{DD} = 75 V, V _{GS} = 0 V | | | 46 | | nC |
| Threshold Gate Charge | Q _{G(TH)} | | | | 12 | | |
| Gate-to-Source Charge | Q_{GS} | | | | 20 | | |
| Gate-to-Drain Charge | Q_{GD} | | | | 7 | | |
| Plateau Voltage | V_{GP} | | | | 6 | | V |
| Output Charge | Q _{OSS} | | | | 116 | | nC |
| SWITCHING CHARACTERISTICS | | | | | | | |
| Turn-On Delay Time | t _{d(ON)} | | | | 27 | | |
| Rise Time | t _r | V_{GS} = 10 V, V_{DD} = 75 V, I_{D} = 54 A, R_{G} = 6 Ω | | | 6 | | ns |
| Turn-Off Delay Time | t _{d(OFF)} | | | | 32 | | |
| Fall Time | t _f | | | | 5 | | |
| DRAIN-SOURCE DIODE CHARACTERISTIC | s | | | | | | |
| Forward Diode Voltage | V_{SD} | $V_{GS} = 0 \text{ V}, I_{S} = 54 \text{ A}$ | T _J = 25°C | | 0.87 | 1.2 | V |
| Reverse Recovery Time | t _{RR} | V _{GS} = 0 V, V _{DD} | = 75 V | | 59 | | ns |
| Reverse Recovery Charge | Q_{RR} | $dI_S/dt = 100 \text{ A/}\mu\text{s}, I_S = 54 \text{ A}$ | | | 111 | | nC |
| Reverse Recovery Time | t _{RR} | V _{GS} = 0 V, V _{DD} = 75 V dI _S /dt = 1000 A/μs, I _S = 54 A | | | 44 | | ns |
| Reverse Recovery Charge | Q _{RR} | | | | 616 | | nC |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTES:

3. $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 \times 1.5 in. board of FR-4 material. $R_{\theta CA}$ is determined by the user's board design.



a) 45° C/W when mounted on a 1 in² pad of 2 oz copper.



b) 115°C/W when mounted on a minimum pad of 2 oz copper.

TYPICAL CHARACTERISTICS

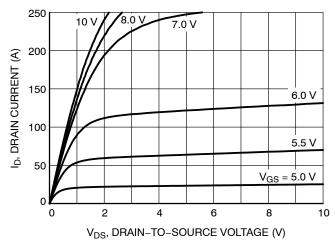


Figure 1. On-Region Characteristics

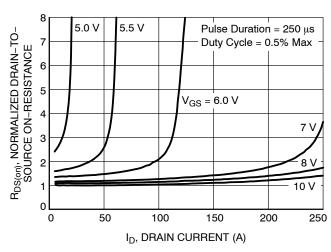


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

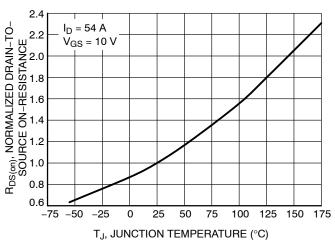


Figure 3. Normalized On–Resistance vs. Junction Temperature

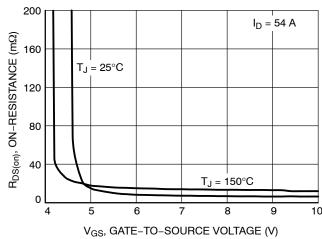


Figure 4. On-Resistance vs. Gate-to-Source Voltage

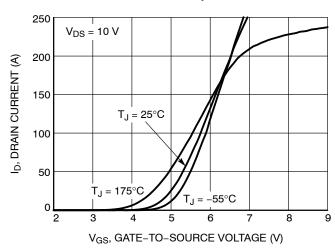


Figure 5. Transfer Characteristics

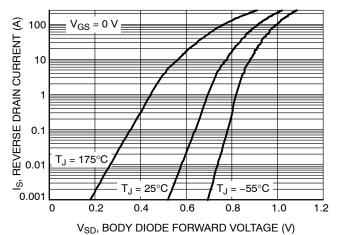


Figure 6. Source-to-Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS

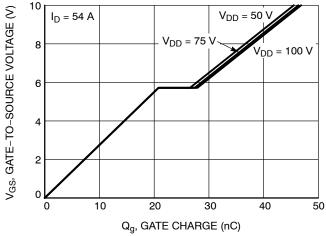


Figure 7. Gate Charge Characteristics

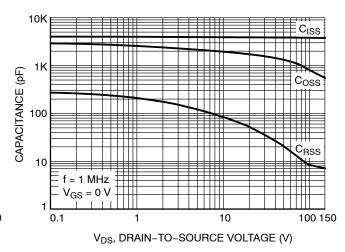


Figure 8. Capacitance vs. Drain-to-Source Voltage

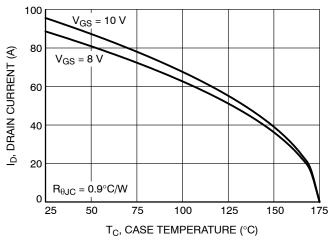


Figure 9. Drain Current vs. Case Temperature

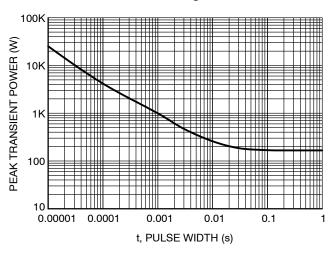


Figure 10. Peak Power

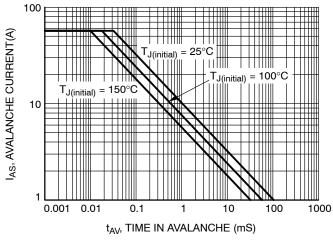


Figure 11. Unclamped Inductive Switching Capability

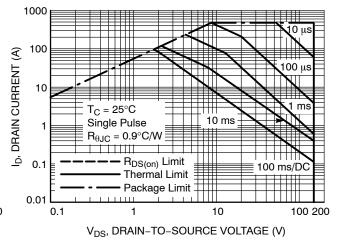


Figure 12. Forward Bias Safe Operating Area

TYPICAL CHARACTERISTICS

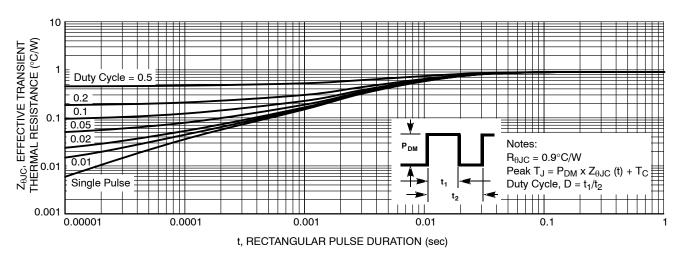
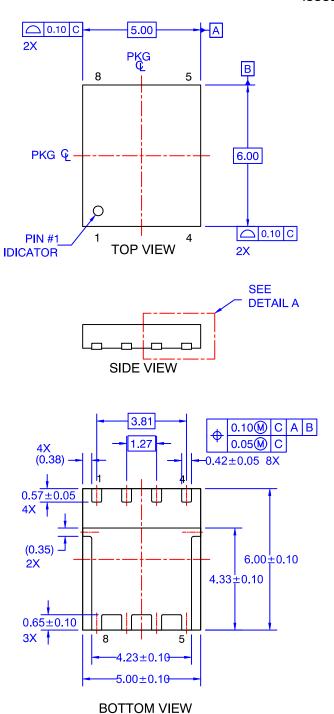
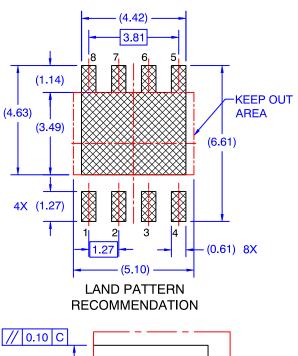


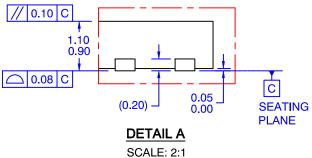
Figure 13. Transient Thermal Impedance

PACKAGE DIMENSIONS

PQFN8 5X6, 1.27P CASE 483AF ISSUE O







NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. AA,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- E) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.

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